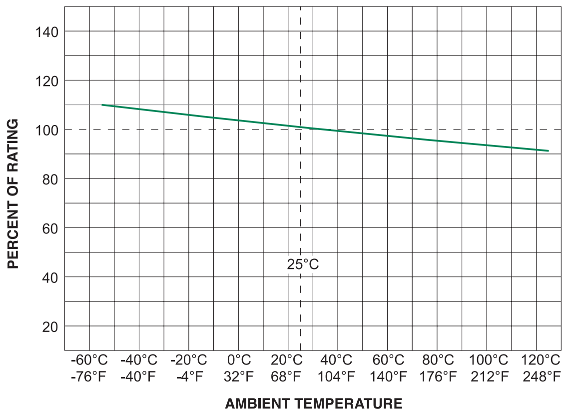
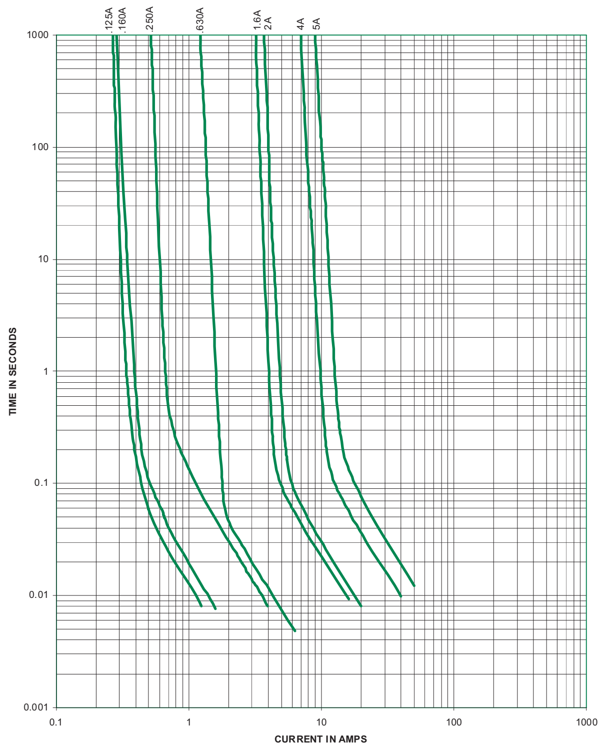
Temperature Re-rating Curve

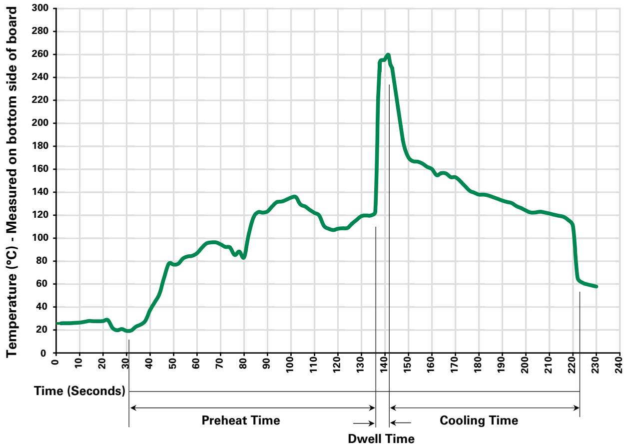


Note:
Rerating depicted in this curve is in addition to the standard derating of 25% for ontinuous operation.

Average Time Current Curves



Soldering Parameters - Wave Soldering



Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum:	100°C
Temperature Maximum:	150°C
Preheat Time:	60-180 seconds
Solder Pot Temperature:	260°C Maximum
Solder Dwell Time:	2-5 seconds

Recommended Hand-Solder Parameters:

Solder Iron Temperature: 350°C +/- 5°C
Heating Time: 5 seconds max.

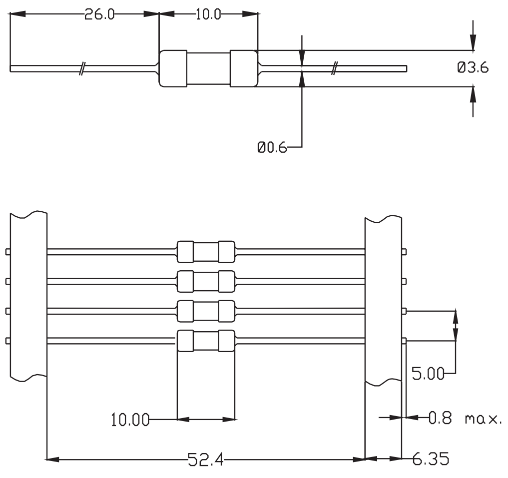
Note: These devices are not recommended for IR or Convection Reflow process.

Product Characteristics

Materials	Body: Ceramic Cap: Nickel Plated Brass Tin Plated Copper
Terminal Strength	MIL-STD-202 Method 211, Test Condition A
Solderability	IEC 60127-2, Annex A
Product Marketing	Body: Brand Logo, Current Rating Characteristic "F",
Packaging	Bulk (1000 pcs/pkg) Tape & Reel (1000 pcs/reel)

Operating Temperature	-55°C to 125°C
Thermal Shock	MIL-STD-202, Method 107 Test Condition B3 (5 cycles -65°C to +125°C)
Vibration	MIL-STD-202, Method 201 (10-55 Hz)
Humidty	MIL-STD-202, Method 106, High Humidity (90-98%RH), Heat (65°C)
Salt Spray	MIL-STD-202, Method 101, Test Condition B

Dimensions



All dimensions in mm

Part Numbering System

0876 xxxx M X E P

Series

Amp Code
Refer to Amp Code column of
Electrical Characteristics Table

Quantity Code
M = 1000

Packaging Code
X = Filler

Option Code
E = Axial Leaded

Lead-free
P = Lead-Free
Others = Special Options
Please call Littelfuse for detail

Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code	Taping Width
		876 Series		
Bulk	Bulk	1000	MXE	N/A
Tape and Reel	EIA 296	1000	MRET1	T1 = 52mm (2.062")